

Application No.: 10/685,261
Amendment Dated: March 25, 2005
Reply to Office Action of: January 25, 2005

END920000181US2

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.-17. Cancelled

18. (Currently amended) A composite structure comprising, in order:

a substrate;

a polymeric layer including a first polymeric material

~~The structure of claim 17~~ in which the first polymeric material is a polyimide;

a layer consisting essentially of silicon-oxide; and

an added layer including a second polymeric material selected from the group consisting of polyimides, polyolefins, polyepoxides, polyurethanes, and polycarbonates.

19. (Original) The structure of claim 18 in which the second polymeric material is a polyimide.

20. (Previously Presented) The structure of claim 18 in which the substrate is an integrated circuit device and the second polymeric material is a polyepoxide.

21. (Original) The structure of claim 20 additionally comprising a chip carrier adjacent to the added layer.

22. (Currently Amended) The structure of claim ~~17~~ 18 additionally comprising a layer of adhesion promoter between the silicon-oxide containing layer and the added layer.

23. (Original) The structure of claim 22 in which the adhesion promoter is selected from the group consisting of 3-amino-propyl-tri-ethoxy-silane, 3-glycidoxy-

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propyl-tri-methoxy-silane, N-(2-amino-ethyl)-3-amino-propyl-tri-ethoxy-silane, 3-amino-propyl-tri-methoxy-silane, N-(2-amino-ethyl)-3-amino-propyl-tri-methoxy-silane, 3-isocyanato-propyl-tri-ethoxy-silane, 10-amino-decyl-tri-methoxy-silane, 11-amino-undecyl-tri-methoxy-silane, n-propyl-tri-methoxy-silane, and phenyl-tri-methoxy-silane.

24.-35. Cancelled

36. (Previously Presented) The structure of claim 20 in which the added layer additionally comprises solid particles of a thermally conductive and electrically insulating material.

37. (Currently Amended) The A-composite structure of claim 21 comprising, in order:

~~a substrate;~~

~~a polymeric layer including a first polymeric material selected from the group consisting of polyimides, polyolefins, polyepoxides, polyurethanes, and polycarbonates;~~

~~a silicon oxide containing layer; and~~

~~in which the an-added layer comprises comprising polyepoxide and solid particles of a thermally conductive and electrically insulating material.~~

38- 39. Canceled